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DISCRETE SEMICONDUCTORS

DATA SHEET

BLW34 UHF linear power transistor

Product specification

August 1986

UHF linear power transistor**BLW34****DESCRIPTION**

N-P-N silicon planar epitaxial transistor primarily intended for use in **linear u.h.f. amplifiers** for television transmitters and transposers. The **excellent d.c. dissipation properties** for class-A operation are obtained by means of diffused emitter ballasting resistors and a multi-base structure, providing an optimum temperature profile on the crystal

area. The combination of optimum thermal design and the application of **gold sandwich metallization** realizes excellent reliability properties.

The transistor has a $\frac{1}{4}$ " capstan envelope with ceramic cap.

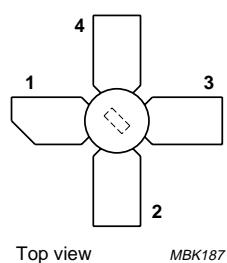
QUICK REFERENCE DATA

R.F. performance

MODE OF OPERATION	f_{vision} MHz	V_{CE} V	I_c mA	T_h °C	$d_{\text{im}}^{(1)}$ dB	$P_o \text{ sync}^{(1)}$ W	G_p dB
class-A; linear amplifier	860	25	600	70	-60	> 1,8	> 9
	860	25	600	25	-60	typ. 2,15	typ. 10,2

Note

- Three-tone test method (vision carrier -8 dB, sound carrier -7 dB, sideband signal -16 dB), zero dB corresponds to peak sync level.

PIN CONFIGURATION

Top view

MBK187

PINNING - SOT122A.

PIN	DESCRIPTION
1	collector
2	emitter
3	base
4	emitter

Fig.1 Simplified outline. SOT122A.

PRODUCT SAFETY This device incorporates beryllium oxide, the dust of which is toxic. The device is entirely safe provided that the BeO disc is not damaged.

UHF linear power transistor

BLW34

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-emitter voltage

(peak value); $V_{BE} = 0$ V_{CESM} max. 50 V

open base

 V_{CEO} max. 30 V

Emitter-base voltage (open collector)

 V_{EBO} max. 4 V

Collector current

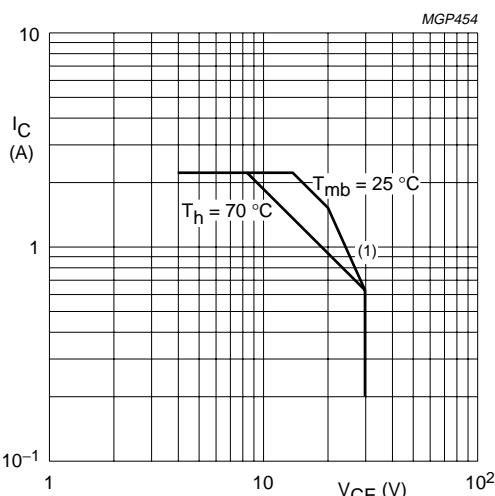
d.c. or average

 I_C max. 2,25 A(peak value); $f > 1$ MHz I_{CM} max. 3,5 ATotal power dissipation at $T_{mb} = 25$ °C P_{tot} max. 31 W

Storage temperature

 T_{stg} -65 to +150 °C

Operating junction temperature

 T_j max. 200 °C

(1) Second breakdown limit (independent of temperature).

Fig.2 D.C. SOAR.

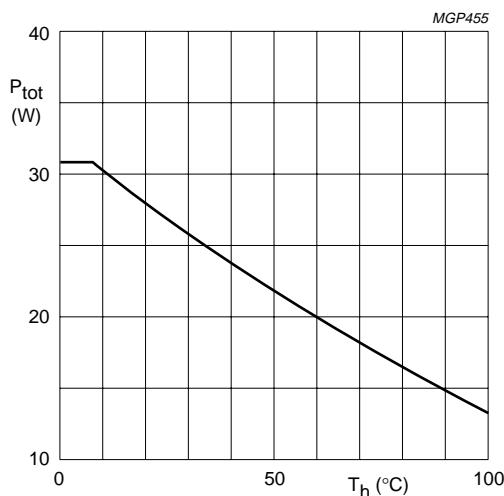


Fig.3 Power derating curve vs. temperature.

THERMAL RESISTANCE (see Fig.4)

From junction to mounting base

(dissipation = 15 W; $T_{mb} = 79$ °C; i.e. $T_h = 70$ °C) $R_{th\ j-mb} = 6,2$ K/W

From mounting base to heatsink

 $R_{th\ mb-h} = 0,6$ K/W

UHF linear power transistor

BLW34

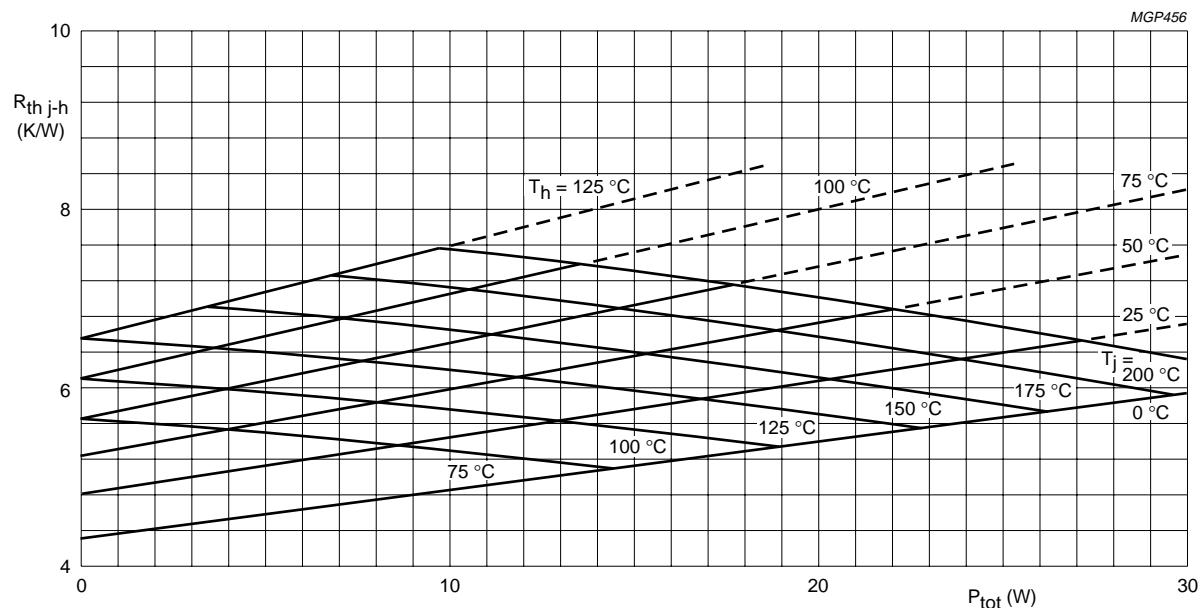


Fig.4 Maximum thermal resistance from junction to heatsink as a function of power dissipation, with heatsink and junction temperature as parameters. ($R_{th\ mb-h} = 0,6$ K/W.)

Example

Nominal class-A operation: $V_{CE} = 25$ V; $I_C = 600$ mA; $T_h = 70$ °C.

Fig.4 shows: $R_{th\ j-h}$ max. 6,75 K/W

T_j max. 170 °C

Typical device: $R_{th\ j-h}$ typ. 5,45 K/W

T_j typ. 152 °C

UHF linear power transistor

BLW34

CHARACTERISTICS $T_j = 25^\circ\text{C}$ unless otherwise specified

Collector-emitter breakdown voltage

$V_{BE} = 0$; $I_C = 8 \text{ mA}$	$V_{(BR)CES}$	>	50	V
open base; $I_C = 60 \text{ mA}$	$V_{(BR)CEO}$	>	30	V

Emitter-base breakdown voltage

open collector; $I_E = 4 \text{ mA}$	$V_{(BR)EBO}$	>	4	V
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Collector cut-off current

$V_{BE} = 0$; $V_{CE} = 30 \text{ V}$	I_{CES}	<	2,0	mA
$V_{BE} = 0$; $V_{CE} = 30 \text{ V}$; $T_j = 175^\circ\text{C}$	I_{CES}	<	5,0	mA

D.C. current gain

$I_C = 600 \text{ mA}$; $V_{CE} = 25 \text{ V}$	h_{FE}	>	20	
		typ.	40	

$I_C = 600 \text{ mA}$; $V_{CE} = 25 \text{ V}$; $T_j = 175^\circ\text{C}$	h_{FE}	<	120	
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Collector-emitter saturation voltage ⁽¹⁾

$I_C = 1,2 \text{ A}$; $I_B = 0,12 \text{ A}$	V_{CEsat}	typ.	450	mV
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Transition frequency at $f = 500 \text{ MHz}$ ⁽²⁾

$-I_E = 0,6 \text{ A}$; $V_{CB} = 25 \text{ V}$	f_T	typ.	3,3	GHz
$-I_E = 1,2 \text{ A}$; $V_{CB} = 25 \text{ V}$	f_T	typ.	3,0	GHz

Collector capacitance at $f = 1 \text{ MHz}$

$I_E = I_e = 0$; $V_{CB} = 25 \text{ V}$	C_c	typ.	13,5	pF
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Feedback capacitance at $f = 1 \text{ MHz}$

$I_C = 40 \text{ mA}$; $V_{CE} = 25 \text{ V}$	C_{re}	typ.	8,4	pF
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Collector-stud capacitance

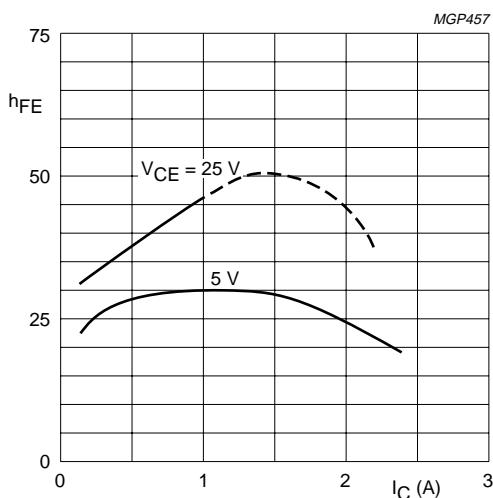
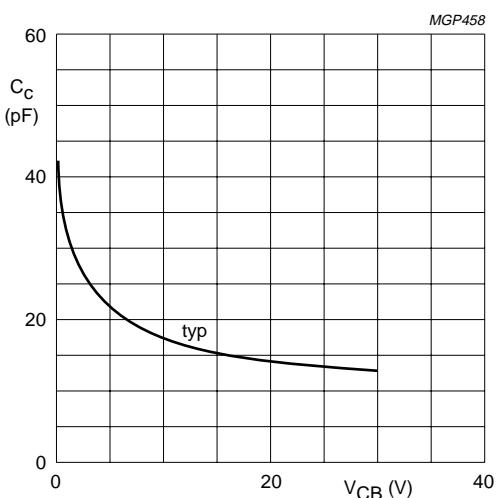
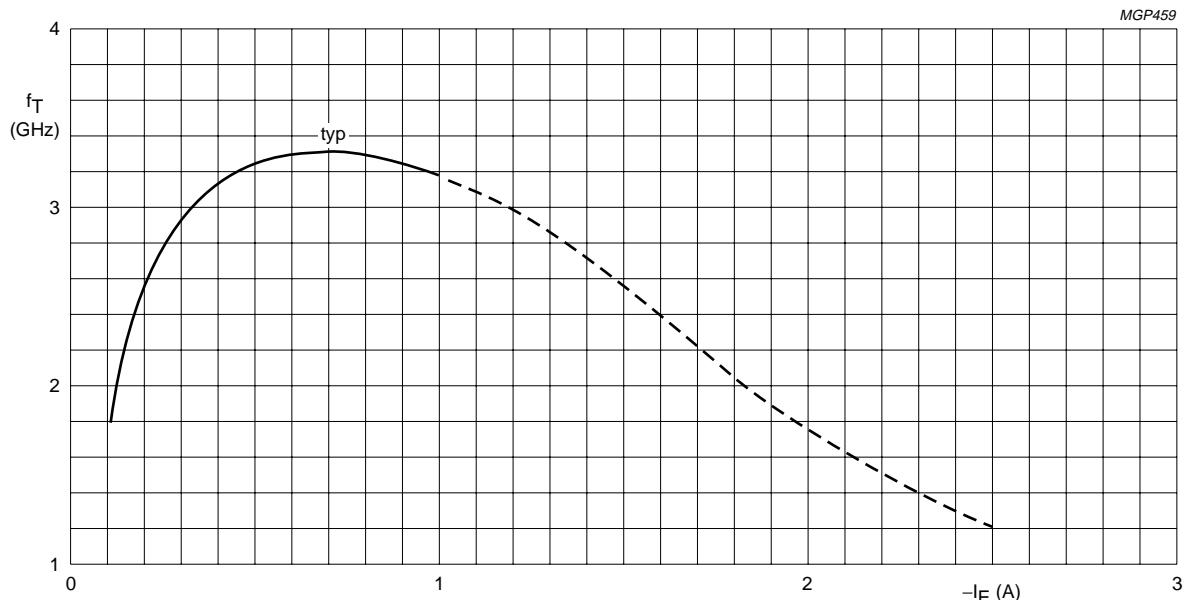
	C_{cs}	typ.	1,2	pF
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Notes

1. Measured under pulse conditions: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0,02$.
2. Measured under pulse conditions: $t_p \leq 50 \mu\text{s}$; $\delta \leq 0,01$.

UHF linear power transistor

BLW34

Fig.5 Typical values; $T_j = 25\text{ }^\circ\text{C}$.Fig.6 $I_E = I_e = 0$; $f = 1\text{ MHz}$; $T_j = 25\text{ }^\circ\text{C}$.Fig.7 $V_{CB} = 25\text{ V}$; $f = 500\text{ MHz}$; $T_j = 25\text{ }^\circ\text{C}$

UHF linear power transistor

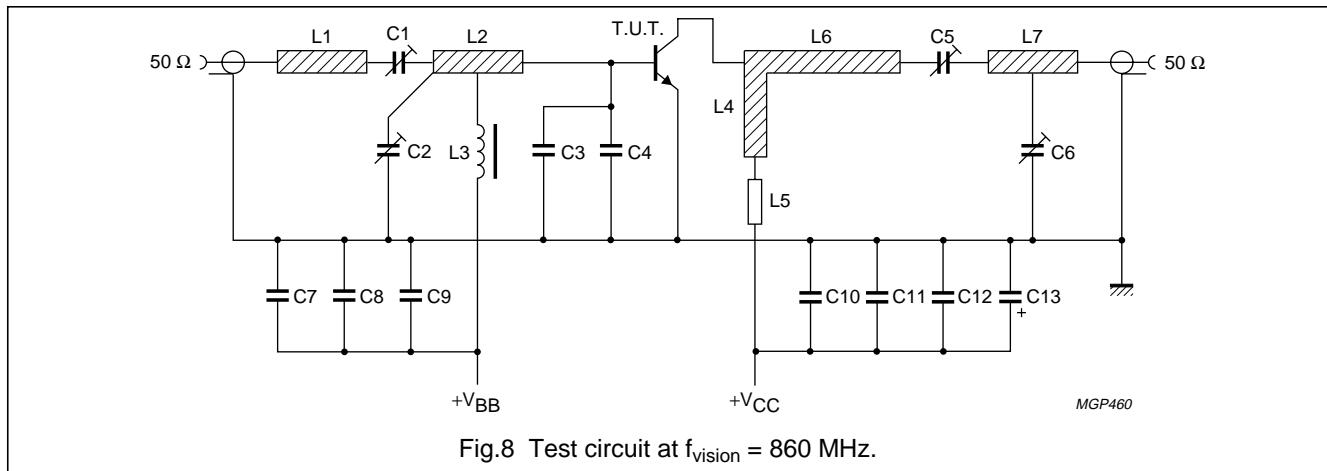
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APPLICATION INFORMATION

f_{vision} (MHz)	V_{CE} (V)	I_C (mA)	T_h ($^{\circ}$ C)	d_{im} (dB) ⁽¹⁾	P_o sync (W) ⁽¹⁾	G_p (dB)
860	25	600	70	-60	> 1,8	> 9
860	25	600	70	-60	typ. 1,9	typ. 10,2
860	25	600	25	-60	typ. 2,15	typ. 10,2

Note

1. Three-tone test method (vision carrier -8 dB, sound carrier -7 dB, sideband signal -16 dB), zero dB corresponds to peak sync level.

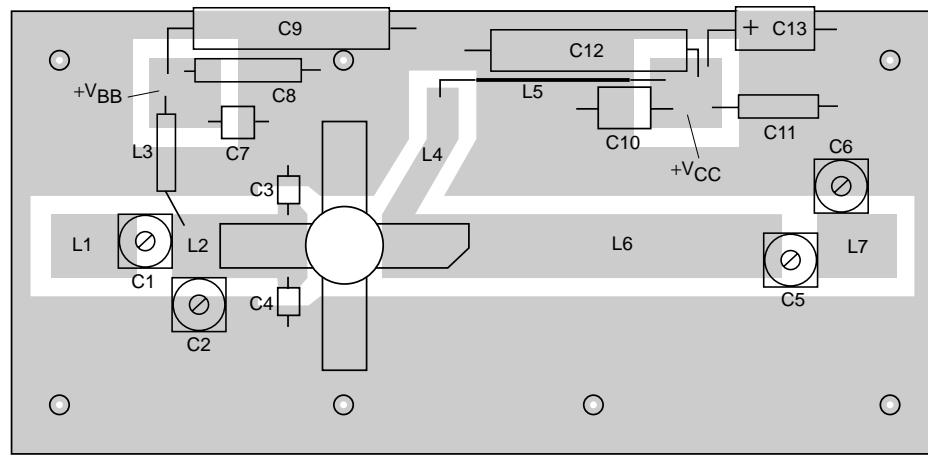
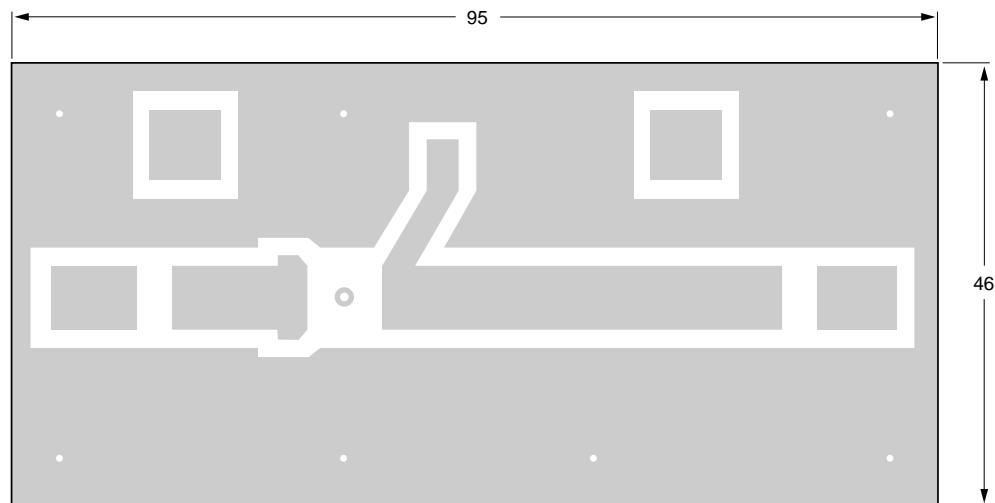


List of components:

- C1 = C5 = 1,8 to 10 pF film dielectric trimmer (cat. no. 2222 809 05002)
- C2 = C6 = 1 to 3,5 pF film dielectric trimmer (cat. no. 2222 809 05001) placed 13,5 mm and 46 mm respectively from transistor edge
- C3 = C4 = 2 pF multilayer ceramic chip capacitor (ATC 100A-2RO-C-PX-50)
- C7 = C10 = 1 nF chip capacitor
- C8 = 100 nF polyester capacitor
- C9 = C12 = 470 nF polyester capacitor
- C11 = 10 nF polyester capacitor
- C13 = 3,3 µF/40 V solid aluminium electrolytic capacitor
- L1 = stripline (9,2 mm × 7,0 mm)
- L2 = stripline (14,2 mm × 7,0 mm)
- L3 = micro choke 0,47 µH (cat. no. 4322 057 04770)
- L4 = stripline (see Fig.9 printed-circuit board layout)
- L5 = 34 mm straight Cu wire (1,0 mm); height above print 3,3 mm
- L6 = stripline (41,0 mm × 7,0 mm)
- L7 = stripline (8,7 mm × 7,0 mm)
- L1; L2; L4; L6 and L7 are striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_r = 2,74$); thickness 1/16".
- Component layout and printed-circuit board for 860 MHz test circuit are shown in Fig.9. For bias circuit see Fig.10.

UHF linear power transistor

BLW34



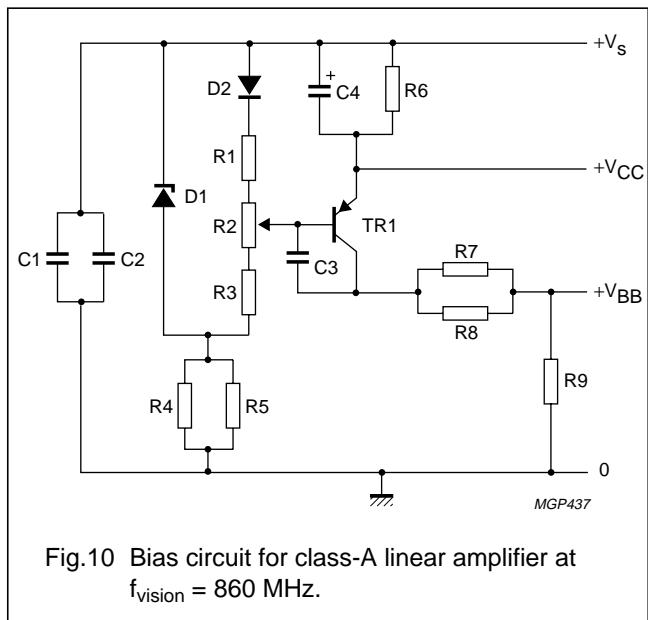
MGP461

Fig.9 Component layout and printed-circuit board for 860 MHz test circuit.

The circuit and the components are situated on one side of the PTFE fibre-glass board, the other side being fully metallized to serve as earth. Earth connections are made by means of hollow rivets, whilst under the emitter leads Cu straps are used for a direct contact between upper and lower sheets.

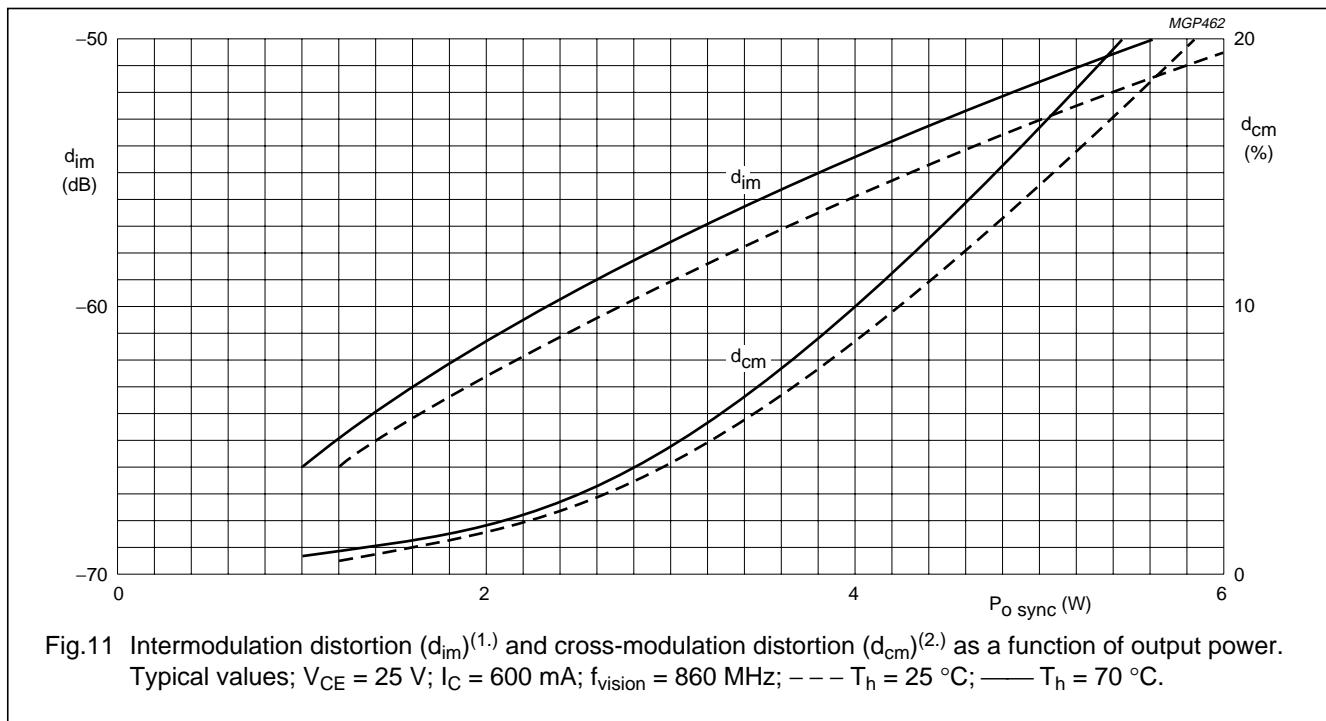
UHF linear power transistor

BLW34



List of components:

C1 = 100 pF ceramic capacitor
 C2 = C3 = 100 nF polyester capacitor
 C4 = 10 $\mu\text{F}/25 \text{ V}$ solid aluminium electrolytic capacitor
 R1 = 150 Ω carbon resistor (0,25 W)
 R2 = 100 Ω preset potentiometer (0,1 W)
 R3 = 82 Ω carbon resistor (0,25 W)
 R4 = R5 = 2,2 k Ω carbon resistor (0,25 W)
 R6 = 2,8 Ω ; parallel connection of
 2 \times 5,6 Ω carbon resistors (0,5 W each)
 R7 = R8 = 820 Ω carbon resistor (0,25 W)
 R9 = 33 Ω carbon resistor (0,25 W)
 D1 = BZY88-C3V3
 D2 = BY206
 TR1 = BD136

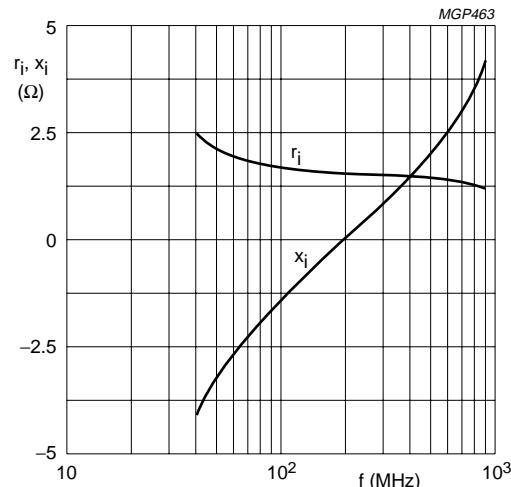


Information for wideband application from 470 to 860 MHz available on request.

- Three-tone test method (vision carrier -8 dB, sound carrier -7 dB, sideband signal -16 dB), zero dB corresponds to peak sync level.
 Intermodulation distortion of input signal $\leq -75 \text{ dB}$.
- Two-tone test method (vision carrier 0 dB, sound carrier -7 dB), zero dB corresponds to peak sync level.
 Cross-modulation distortion (d_{cm}) is the voltage variation (%) of sound carrier when vision carrier is switched from 0 dB to -20 dB.

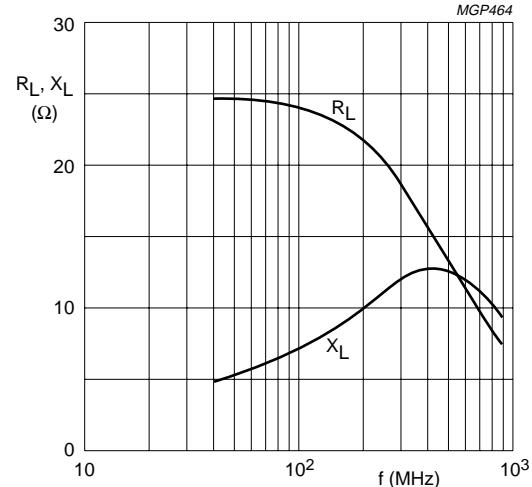
UHF linear power transistor

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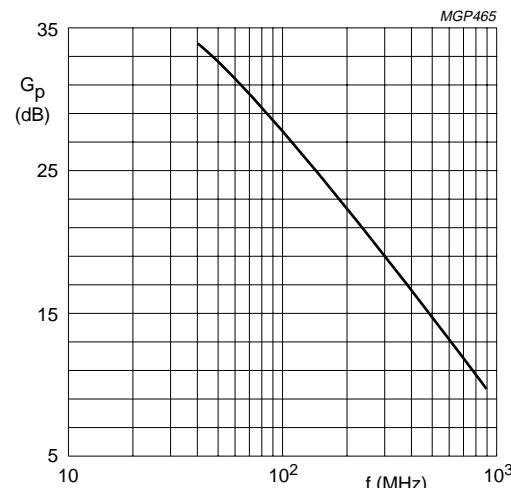
Typical values; $V_{CE} = 25$ V;
 $I_C = 600$ mA; $T_h = 70$ °C.

Fig.12 Input impedance (series components).



Typical values; $V_{CE} = 25$ V;
 $I_C = 600$ mA; $T_h = 70$ °C.

Fig.13 Load impedance (series components).



Typical values; $V_{CE} = 25$ V;
 $I_C = 600$ mA; $T_h = 70$ °C.

Fig.14

Ruggedness

The BLW34 is capable of withstanding a load mismatch (VSWR = 50 through all phases) under the following conditions:

$f = 860$ MHz; $V_{CE} = 25$ V; $I_C = 600$ mA;
 $T_h = 70$ °C and $P_L = 4$ W.

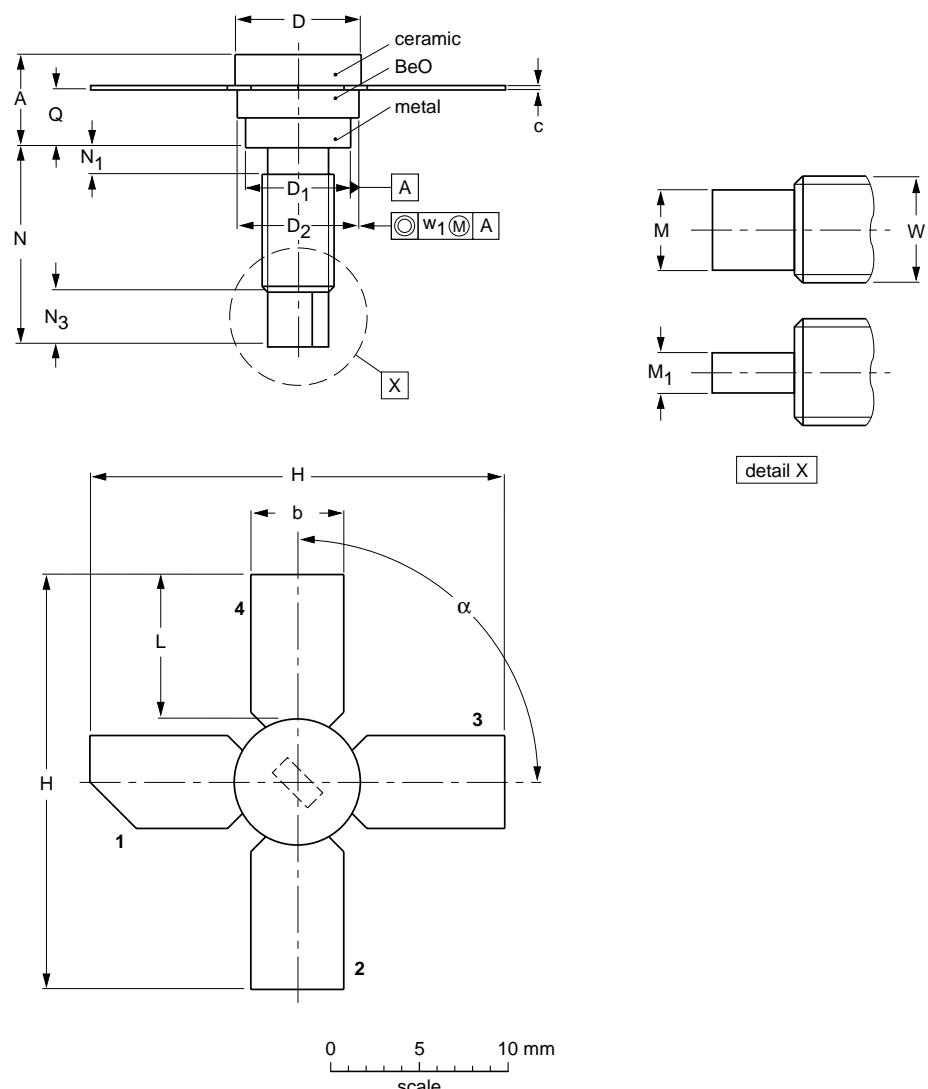
UHF linear power transistor

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PACKAGE OUTLINE

Studded ceramic package; 4 leads

SOT122A



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D ₁	D ₂	H	L	M ₁	M	N	N ₁ max.	N ₃	Q	W	w ₁	α
mm	5.97 4.74	5.85 5.58	0.18 0.14	7.50 7.23	6.48 6.22	7.24 6.93	27.56 25.78	9.91 9.14	3.18 2.66	1.66 1.39	11.82 11.04	1.02	3.86 2.92	3.38 2.74	8-32 UNC	0.381	90°

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT122A							97-04-18

UHF linear power transistor**BLW34****DEFINITIONS**

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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